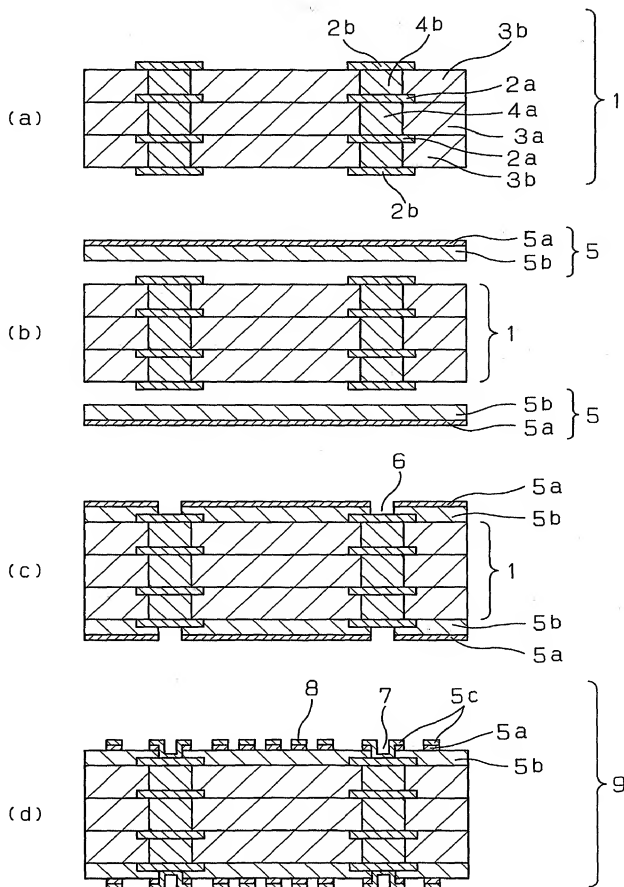
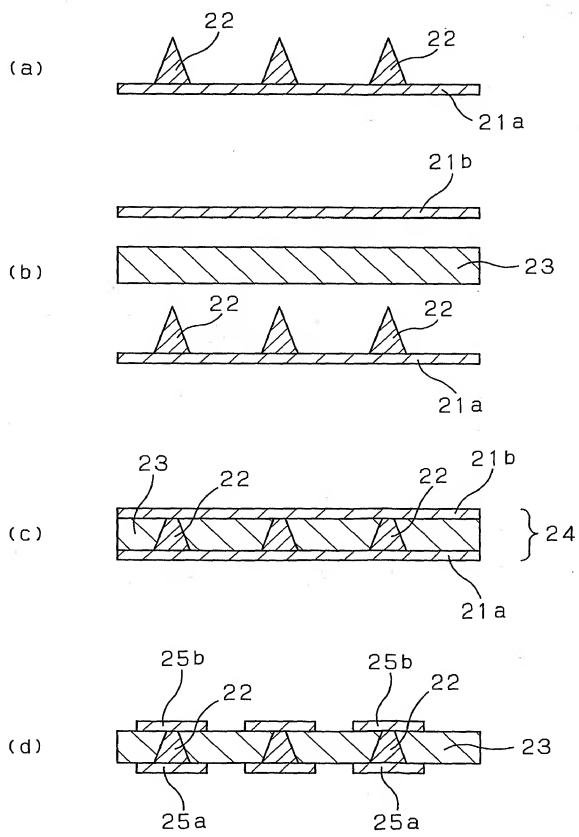


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Fig. 1

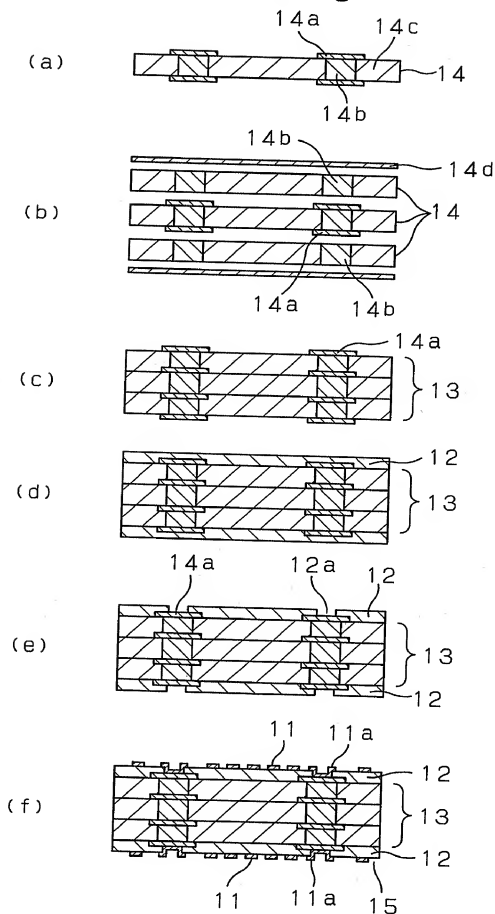


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Fig. 2



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Fig. 3



Key to Reference Alphanumeric Characters

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- | | | |
|----|-----|---|
| | 1 | Inner Layer Material |
| | 2 | Inner Conductive Pattern |
| | 2a | First Inner Conductive Pattern |
| 10 | 2b | Second Inner Conductive Pattern |
| | 3 | Insulating Substrate for Inner Layer Material |
| | 3a | First Insulating Substrate |
| | 3b | Second Insulating Substrate |
| | 4 | Conductive Paste and Interstitial Via Hole |
| 15 | 4a | First Conductive Paste, Interstitial Via Hole |
| | 4b | Second Conductive Paste, Interstitial Via Hole |
| | 5 | Metal Foil with Insulating Resin |
| | 5a | Metal Foil |
| | 5b | Insulating Resin |
| 20 | 5c | Metal Plating Layer |
| | 6 | Non-through Hole |
| | 7 | Surface Via Hole (SVH) with Metal Plating Applied to Non-through Hole |
| | 8 | Outer Conductive Pattern |
| 25 | 9 | Multilayer Printed Wiring Board |
| | 21a | First Copper Foil |
| | 21b | Second Copper Foil |
| | 22 | Conductor Projection |
| | 23 | Aramid Nonwoven Fabric Base Material Epoxy Resin Prepreg |
| 30 | 24 | Laminated Board for Inner Layer |

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- 25 Inner Conductor Circuit
- 25a First Inner Conductor Circuit, First Inner Conductive Pattern
- 25b Second Inner Conductor Circuit, Second Inner Conductive Pattern

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